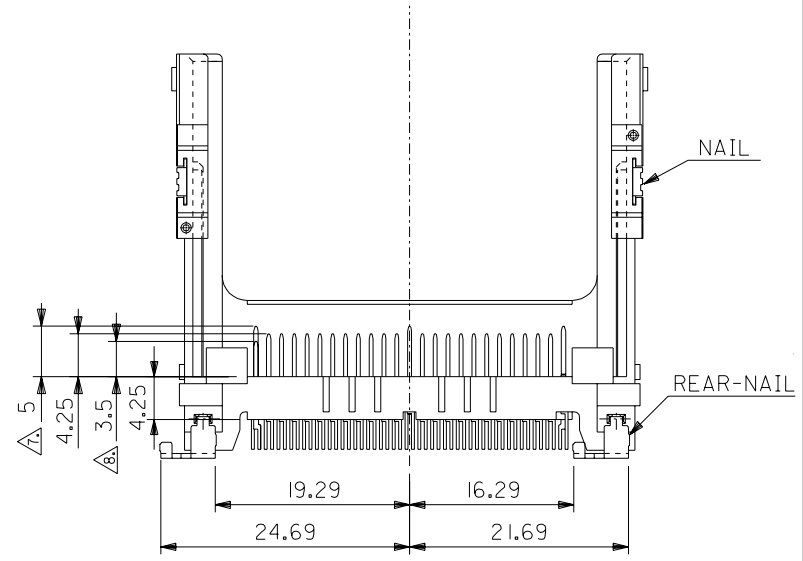
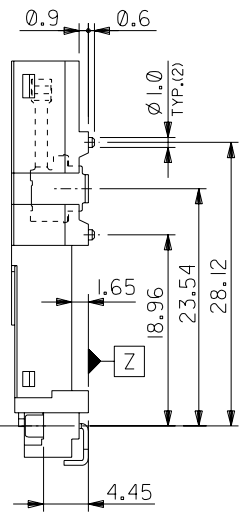
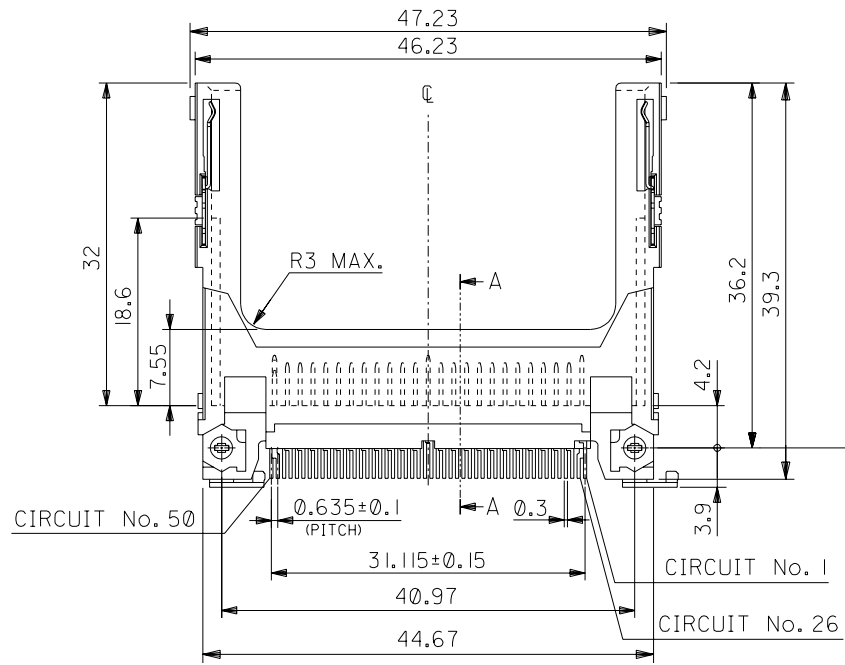
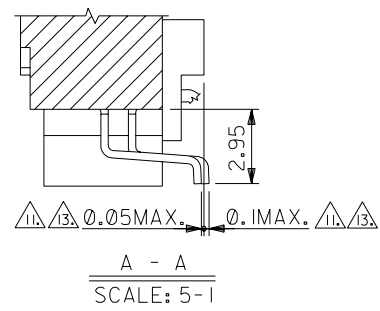
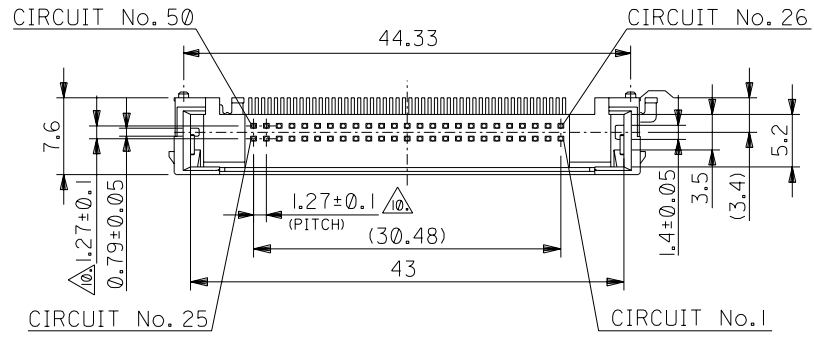


DWG. NO. SD-55358-014



DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:
RELEASED EC NO. J2004-3952 DRWN: M.NABEI '04/04/22 CHK: K.TOJO '04/04/22 APPR: M.SASAO '04/04/22			

DESCRIPTION	MATERIAL 材料	FINISH 仕上り	WIRE RANGE 適用層被範囲	INS. RANGE 被覆外径
	SEE NOTES	SEE NOTES	#	#

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 30 UNDER 以上 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

55358-5028		55358-5029		55358-50**	
HARD TRAY PACKAGE		MATERIAL No.		MODEL No.	
SCALE 2 - 1	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input type="checkbox"/> mm <input checked="" type="checkbox"/> INCH ONLY		SHT	REV
DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-			
CHECKED BY & DATE K.TOJO '04/04/22		M.OLEX MOLEX INCORPORATED			
APPROVED BY & DATE M. Sasao '04/04/22		MATERIAL NO. SEE CHART	DRAWING NO. SD-55358-014	SHEET NO. 1 OF 2	REVISION REVISE ON CAD ONLY
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

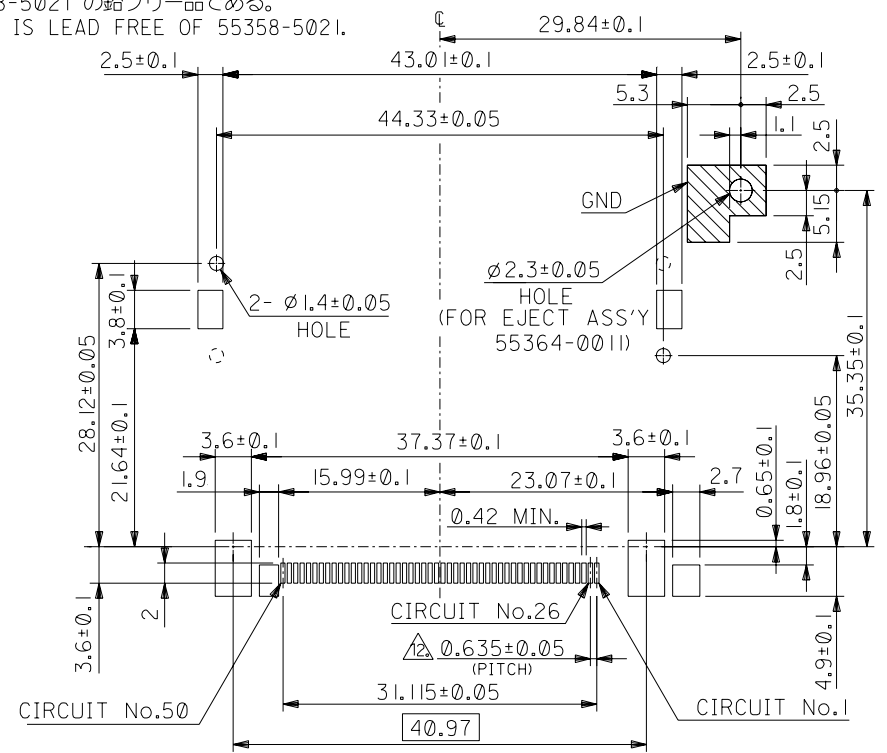
SD-55358-014.S01

DWG. NO. SD-55358-014

DO NOT SCALE DRAWING

- 8 7 6 5 4 3 2 1
- 注) NOTES
1. 材質 MATERIAL  
 ハウジング: ガラス入りLCP UL94V-0  
 HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0  
 ピン: リン青銅  
 PIN: PHOSPHOR BRONZE  
 ネール: リン青銅 (t0.3)  
 NAIL: PHOSPHOR BRONZE (t0.3)  
 リヤネール: リン青銅 (t0.48)  
 REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING  
 ピン PIN 接点部 : パラジウムニッケル下地、金メッキ  
 CONTACT AREA: GOLD OVER PALLADIUM-NICKEL  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 ネール NAIL 接点部 : 金メッキ  
 CONTACT AREA: GOLD  
 半田付け部: 錫メッキ  
 SOLDER TAIL AREA: TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL  
 リヤネール REAR-NAIL 錫メッキ  
 TIN  
 下地メッキ: ニッケルメッキ  
 UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚 : t=0.8 MIN.  
 RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚 : 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)  
 RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅 : 42.8±0.1  
 RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒  
 HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26  
 THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ 0.1 MAX.とする。  
 PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。  
 THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ 0.05 下へ 0.1 の範囲にあり、且つソルダータールの平坦度は、0.1 MAX. とし、テール先端にて測定する。  
 SOLDER TAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDER TAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDER TAILS TIP.
12. 公差非累積  
 NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。  
 TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5021 の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 55358-5021.



基板推奨寸法  
 RECOMMENDED P.C.B. LAYOUT

EC NO. DRAWN: CHK'g: APPR'g:	EC NO. DRAWN: CHK'g: APPR'g:	EC NO. DRAWN: CHK'g: APPR'g:	EC NO. DRAWN: CHK'g: APPR'g:	EC NO. DRAWN: CHK'g: APPR'g:	EC NO. DRAWN: CHK'g: APPR'g:	DESCRIPTION	MATERIAL 材料	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE	DESIGN UNITS	MODEL NO.	DIMENSIONS:		SHT	REV
							SEE NOTES	10 UNDER 未満	±0.2	2 - 1	mm □ INCH	THIRD ANGLE PROJECTION	mm □ INCH	mm □ mm □ mm	INCH □ mm □ mm
							SEE NOTES	10 OVER 以上	±0.25	DRAWN BY & DATE M.NABEI '04/04/22	TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-				
						FINISH 仕上げ	SEE NOTES	30 UNDER 未満	±0.3	CHECKED BY & DATE K.TOJO '04/04/22					
						WIRE RANGE 適用電線範囲	—	30 OVER 以上	±0.3	APPROVED BY & DATE M. Saad '04/04/22		MOLEX INCORPORATED			
						REV	INS. RANGE 被覆外径	—	ANGLE 角度	±3°	CAD FILENAME SD-55358-014.S02	MATERIAL NO. —	DRAWING NO. SD-55358-014	SHEET NO. 2	SIZE B
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SD-55358-014.S02